L Numb	er Hit		DB	Time stamp
1		4 4783428.pn. 4878108.pn. 6006981.pn. 6646329.pn.	USPAT; US-PGPUB	2004/05/19 10:22
2	252	438/463.ccls. 438/464.ccls.	USPAT; US-PGPUB	2004/05/19 10:34
3		3 (438/15.ccls. 438/17.ccls. 438/111.ccls. 438/113.ccls	USPAT;	2004/05/19 11:12
		438/463.ccls. 438/464.ccls.) and (leadframe (lead adj frame) with laser) and (tape with reel) and (((semiconductor	US-PGPUB	
4	· .	adj device) ic (integrated adj circuit)) with test\$6) (leadframe (lead adj frame) with laser) same (tape with	USPAT;	2004/05/10 10 15
		reel) same (((semiconductor adj device) ic (integrated adj circuit)) with test\$6)	US-PGPUB	2004/05/19 10:46
5	385		USPAT;	2004/05/19 11:00
6	2	((leadframe (lead adj frame)) with laser) and (tape with reel) and (((semiconductor adj device) ic (integrated adj	US-PGPUB USPAT;	2004/05/19 10:44
		Circuit)) with test\$6)	US-PGPUB	
8	. 20	(438/15.ccls. 438/17.ccls. 438/111.ccls. 438/113.ccls. 438/463.ccls. 438/464.ccls.) and (((leadframe (lead adj	USPAT;	2004/05/19 10:47
		(frame)) with laser))	US-PGPUB	
9	7	(dic\$6 cut\$7))	USPAT; US-PGPUB	2004/05/19 11:11
10	83	((leadframe (lead adj frame)) with strip) and (laser with (dic\$6 cut\$7))	USPAT; US-PGPUB	2004/05/19 12:23
11	0	(((leadframe (lead adj frame)) with strip) and (laser with	USPAT;	2004/05/19 12:13
		(dic\$6 cut\$7))) and (tape with reel) and (((semiconductor adj device) ic (integrated adj circuit)) with test\$6)	US-PGPUB.	
13	13	(((leadframe (lead adj frame)) with strip) and (laser with (dic\$6 cut\$7))) and ((tape with reel) (((semiconductor adj	USPAT; US-PGPUB	2004/05/19 12:25
14	7	device) ic (integrated adj circuit)) with test\$6))	r.	
17		(((leadframe (lead adj frame)) with strip) and (laser with (dic\$6 cut\$7))) and (tape reel spool) and (((semiconductor adj device) ic (integrated adj circuit)) with test\$6)	USPAT; US-PGPUB	2004/05/19 12:13
15	158	(leadframe (lead adj frame)) same (laser with (dic\$6 cut\$7))	USPAT; US-PGPUB	2004/05/19 12:47
16	13	((leadframe (lead adj frame)) same (laser with (dic\$6 cut\$7))) and ((tape with reel) (((semiconductor adj device)	USPAT; US-PGPUB	2004/05/19 12:25
19	0	(4783428.pn. 4878108.pn. 6006981.pn. 6646329.pn.) and	USPAT;	2004/05/19 12:43
20	1	underfill 20020171126.pn. and underfill	US-PGPUB USPAT;	2004/05/19 12:43
21	188	(leadframe (lead adj frame)) and (laser with (dic\$6 cut\$7))	US-PGPUB EPO; JPO;	
			DERWENT; IBM_TDB	2004/05/19 12:47
22	3	(leadframe (lead adj frame)) and (laser with (dic\$6 cut\$7)) and test\$6	EPO; JPO; DERWENT;	2004/05/19 12:56
23	12	(leadframe (lead adj frame)) and (laser with (dic\$6 cut\$7)) and (tape reel spool)	IBM_TDB EPO; JPO; DERWENT;	2004/05/19 12:56
48	2	(strip near2 test\$6) same (isolat\$6 near2 gate)	IBM_TDB USPAT;	2004/05/19 15:54
49	97	test\$6 with (isolat\$6 near2 gate)	US-PGPUB USPAT;	2004/05/19 16:29
50	89	(test\$6 with (isolat\$6 near2 gate)) and (semiconductor	US-PGPUB USPAT;	2004/05/19 16:30
52	107,	silicon wafer package integrated) (test\$6 with (pad near2 gate)) and (semiconductor silicon	US-PGPUB USPAT;	2004/05/19 16:30
53	1	wafer package integrated) (strip near2 test\$6) with (pad near2 gate)	US-PGPUB	
54			USPAT; US-PGPUB	2004/05/19 16:31
<u> </u>	1	(strip near2 test\$6) same (pad near2 gate)	USPAT; US-PGPUB	2004/05/19 16:31

	51	112	tootte with (and and a		
Į.	21	113	test\$6 with (pad near2 gate)	USPAT;	2004/0E/10 1C-22
ı				,	2004/05/19 16:32
L				US-PGPUB	